

Title (en)
ELECTRONIC COMPONENT MODULE

Title (de)
ELEKTRONISCHES BAUELEMENTMODUL

Title (fr)
MODULE COMPOSANT ÉLECTRONIQUE

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EP 2008305 A2 20081231 (DE)

Application
EP 07727991 A 20070411

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• EP 2007053523 W 20070411
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Abstract (en)
[origin: WO2007118831A2] The invention relates to an electronic component module, comprising at least one first multi-layer circuit board module (21, 22; 31, 32; 41, 42) and a cooling arrangement (23, 33, 43), the cooling arrangement (23, 33, 43) being in contact with an upper side of the circuit board module (21, 22; 31, 32; 41, 42). The cooling arrangement (23, 33, 43) is designed such that waste heat generated during operation of the electronic component module (2, 3, 4) is extracted in a lateral direction with relation to the arrangement of the circuit board module (21, 22; 31, 32; 41, 42) by means of the cooling arrangement (23, 33, 43).

IPC 8 full level
H01L 25/065 (2006.01); **H01L 25/07** (2006.01)

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C-Set (source: EP US)
1. **H01L 2224/48091 + H01L 2924/00014**
2. **H01L 2224/48472 + H01L 2224/48091 + H01L 2924/00**

Citation (search report)
See references of WO 2007118831A2

Designated contracting state (EPC)
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Designated extension state (EPC)
AL BA HR MK RS

DOCDB simple family (publication)
DE 102006018161 A1 20071025; CA 2650547 A1 20071025; CN 101427371 A 20090506; CN 101427371 B 20111214; EP 2008305 A2 20081231; JP 2009534822 A 20090924; JP 4940295 B2 20120530; KR 101478518 B1 20150106; KR 20090005190 A 20090112; TW 200810677 A 20080216; US 2009097208 A1 20090416; US 8164904 B2 20120424; WO 2007118831 A2 20071025; WO 2007118831 A3 20080221

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